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Application ID: 10665651 *10665651*

Title of Invention: THIN AND HEAT RADIANT
SEMICONDUCTOR PACKAGE AND
METHOD FOR MANUFACTURING

First Named Inventor: Jae Ku

Domestic/Foreign Application: Domestic Application

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Electronic Version v1.1

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Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING	
Application Number: 10/665651 *10/665651*		
Date: 2003-09-19		
First Named Applicant: Jae Hun Ku		
Confirmation Number: 6079		
Attorney Docket Number: AMKOR041G		
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Submitted by:	Elec. Sign.	Sign. Capacity
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Comments	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING						
 Application Number: 10/665651 *10/665651* Confirmation Number: 6079 First Named Applicant: Jae Ku Attorney Docket Number: AMKOR041G Art Unit: 2811 Search string: (5221642 or 5250841 or 5252853 or 5258094 or 5266834 or 5273938 or 5277972 or 5278446 or 5279029 or 5294897 or 5327008 or 5332864 or 5335771 or 5336931 or 5343076 or 5358905 or 5365106 or 5381042 or 5391439 or 5406124 or 5410180 or 5414299 or 5424576 or 5428248 or 5435057 or 5444301 or 5452511 or 5454905 or 5474958 or 5484274 or 5493151 or 5508556 or 5517056 or 5521429 or 5528076 or 5534467 or 5539251 or 5543657 or 5544412 or 5545923 or 5581122 or 5592019 or 5592025 or 5594274 or 5595934 or 5604376 or 5608267 or 5625222 or 5633528 or 5639990).pn. US Patent Documents Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date